

Ultra-low Capacitance ESD Protection Diode

Features

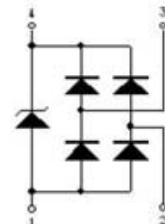
- Uni-directional ESD protection of two lines
 - Low capacitance: 0.8pF(Max)
 - Low reverse stand-off voltage: 5V
 - Low reverse clamping voltage
 - Low leakage current
 - Fast response time
 - JESD22-A114-B ESD Rating of class 3B per human body model
 - IEC 61000-4-2 Level 4 ESD protection



SOT-143

Applications

- USB2.0 power & data line protection
 - WLAN/LAN equipment
 - Mobile phone
 - Video line protection
 - Microcontroller input Protection
 - ISDN S/T Interface



Schematic Diagram

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
IEC 61000-4-2 ESD Voltage(I/O to GND & V _{CC} to GND)	V _{ESD} ⁽¹⁾	Air Model ±25	kV
Contact Model ±25			
JESD22-A114-B ESD Voltage (I/O to GND & V _{CC} to GND)		Per Human Body Model ±16	
ESD Voltage(I/O to GND & V _{CC} to GND)		Machine Model ±0.4	
Peak Pulse Power	P _{PP} ⁽²⁾	90	W
Peak Pulse Current	I _{PP} ⁽²⁾	3.5	A
Lead Solder Temperature – Maximum (10 Second Duration)	T _L	260	°C
Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Note:

(1) Device stressed with ten non-repetitive ESD pulses.

(2) Non-repetitive current pulse 8/20μs exponential decay waveform according to IEC61000-4-5.

Electrical Characteristics per Line ($T_A=25^\circ\text{C}$ unless otherwise specified)

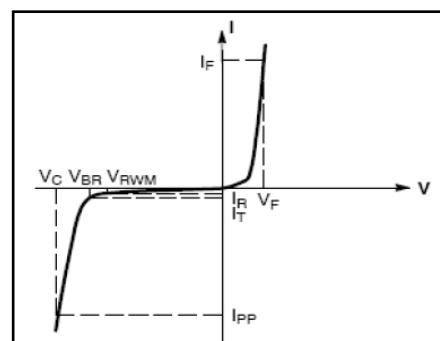
Parameter	Symbol	Test Conditions	Min	Max	Unit
Per channel(I/O to GND unless otherwise specified)					
Reverse stand off voltage	$V_{RWM}^{(1)}$			5	V
Breakdown voltage	$V_{(BR)}$	$I_T=1\text{mA}$	6	10	V
		$I_T=1\text{mA}$ V_{CC} to GND	5	12	V
Reverse leakage current	I_R	$V_{RWM}=5\text{V}$ (I/O to GND & V_{CC} to GND)		1	μA
Forward voltage	V_F	$I_F=10\text{mA}$ (I/O to GND & V_{CC} to GND)	0.4	1.5	V
Clamping voltage	$V_C^{(2)}$	$I_{PP}=1\text{A}$ (I/O to GND & V_{CC} to GND)		13	V
		$I_{PP}=3.5\text{A}$ (I/O to GND & V_{CC} to GND)		25	V
Junction capacitance	C_J	$V_R=0\text{V}, f=1\text{MHz}$		0.8	pF
		$V_R=0\text{V}, f=1\text{MHz}$, I/O to I/O		0.4	pF

(1).Other voltages available upon request.

(2).Non-repetitive current pulse 8/20 μs exponential decay waveform according to IEC61000-4-5

Electrical Parameter

Symbol	Parameter
V_C	Clamping Voltage @ I_{PP}
I_{PP}	Peak Pulse Current
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_R	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Reverse Standoff Voltage
V_F	Forward Voltage@ I_F
I_F	Forward Current



V-I characteristics for a uni-directional TVS



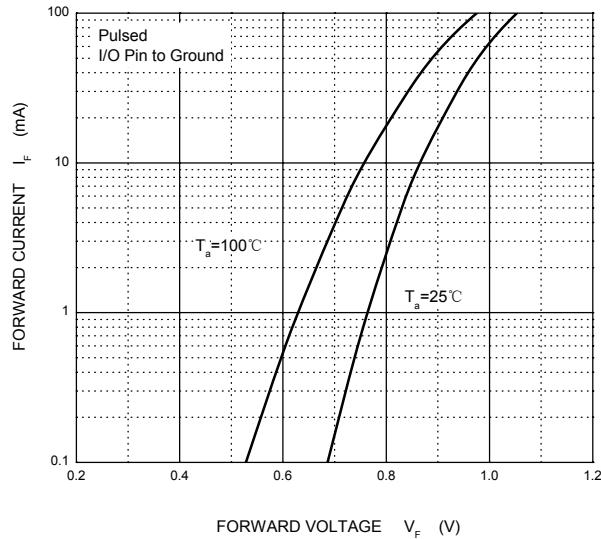
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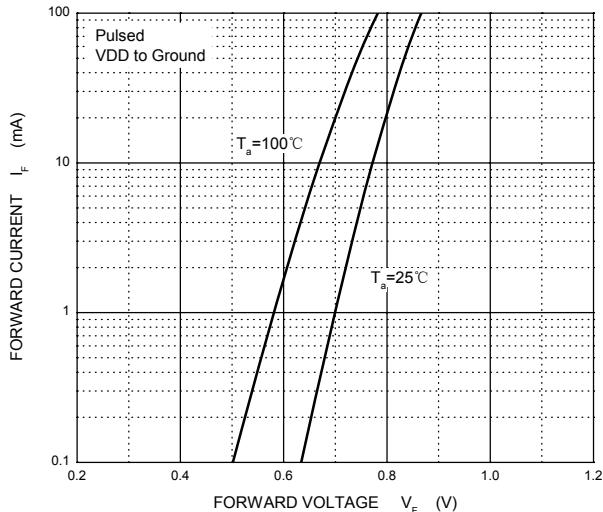
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Typical Characteristics

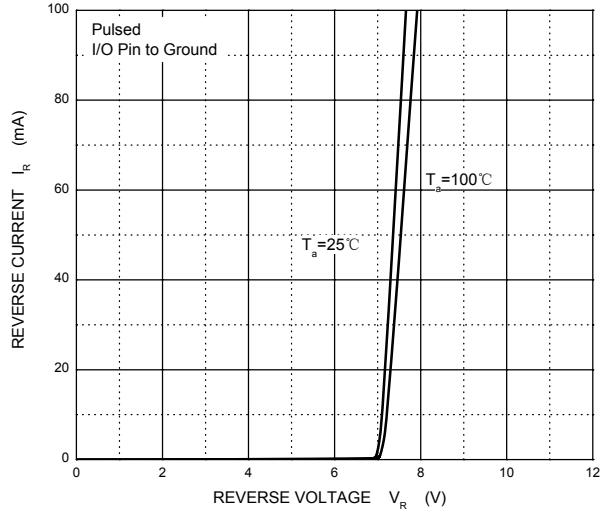
Forward Characteristics



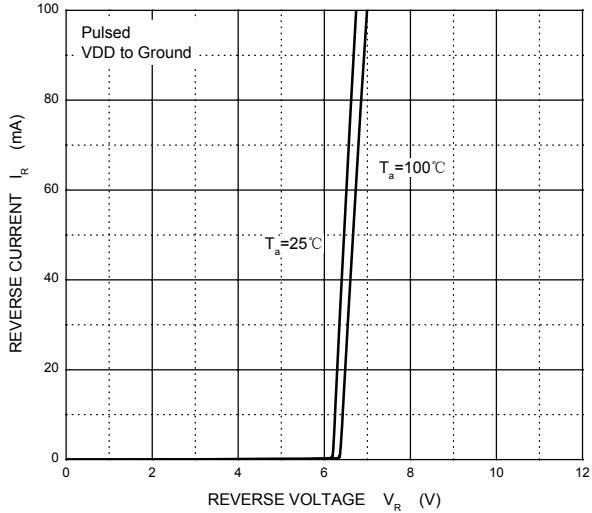
Forward Characteristics



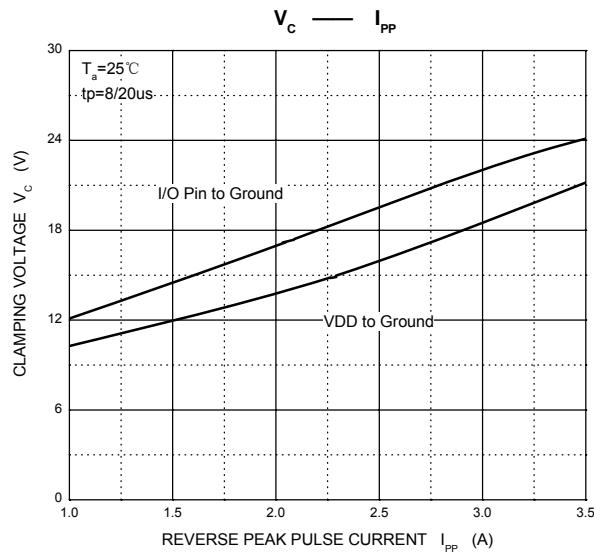
Reverse Characteristics



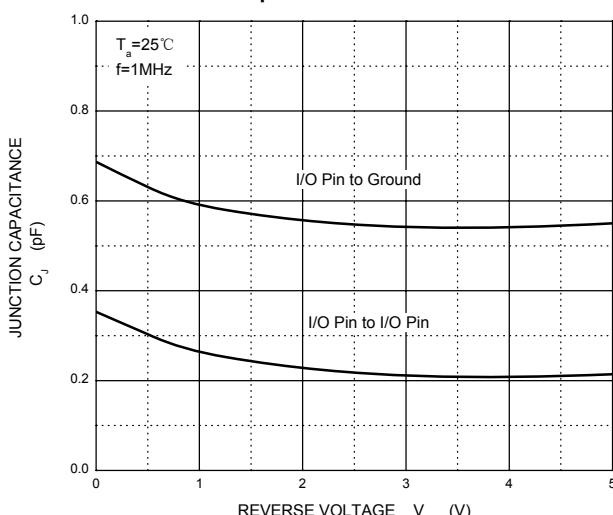
Reverse Characteristics



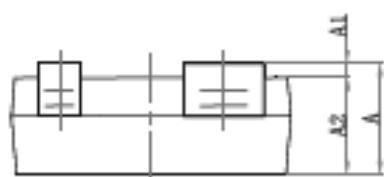
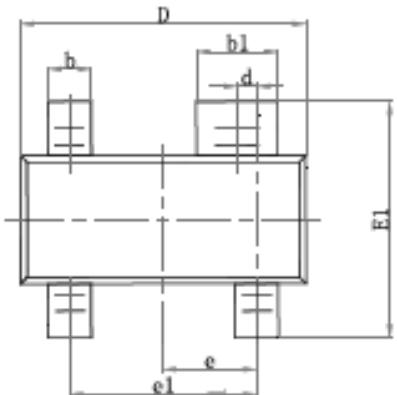
V_C — I_{PP}



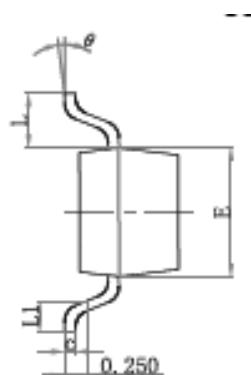
Capacitance Characteristics



Product Dimensions



SOT-143



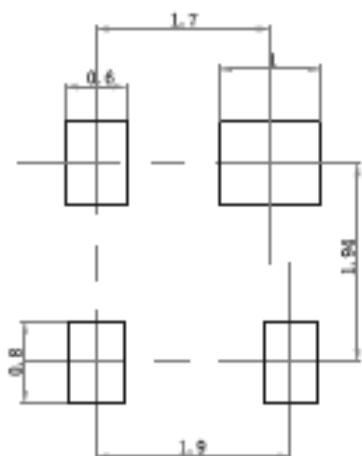
Dimensions In Millimeters

Symbol	Dimensions In Millimeters	Dimensions In Inches		
	Min.	Max.		
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
b1	0.750	0.900	0.030	0.035
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
d	0.200 TYP.		0.008 TYP.	
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

Suggested Pad Layout



Marking

